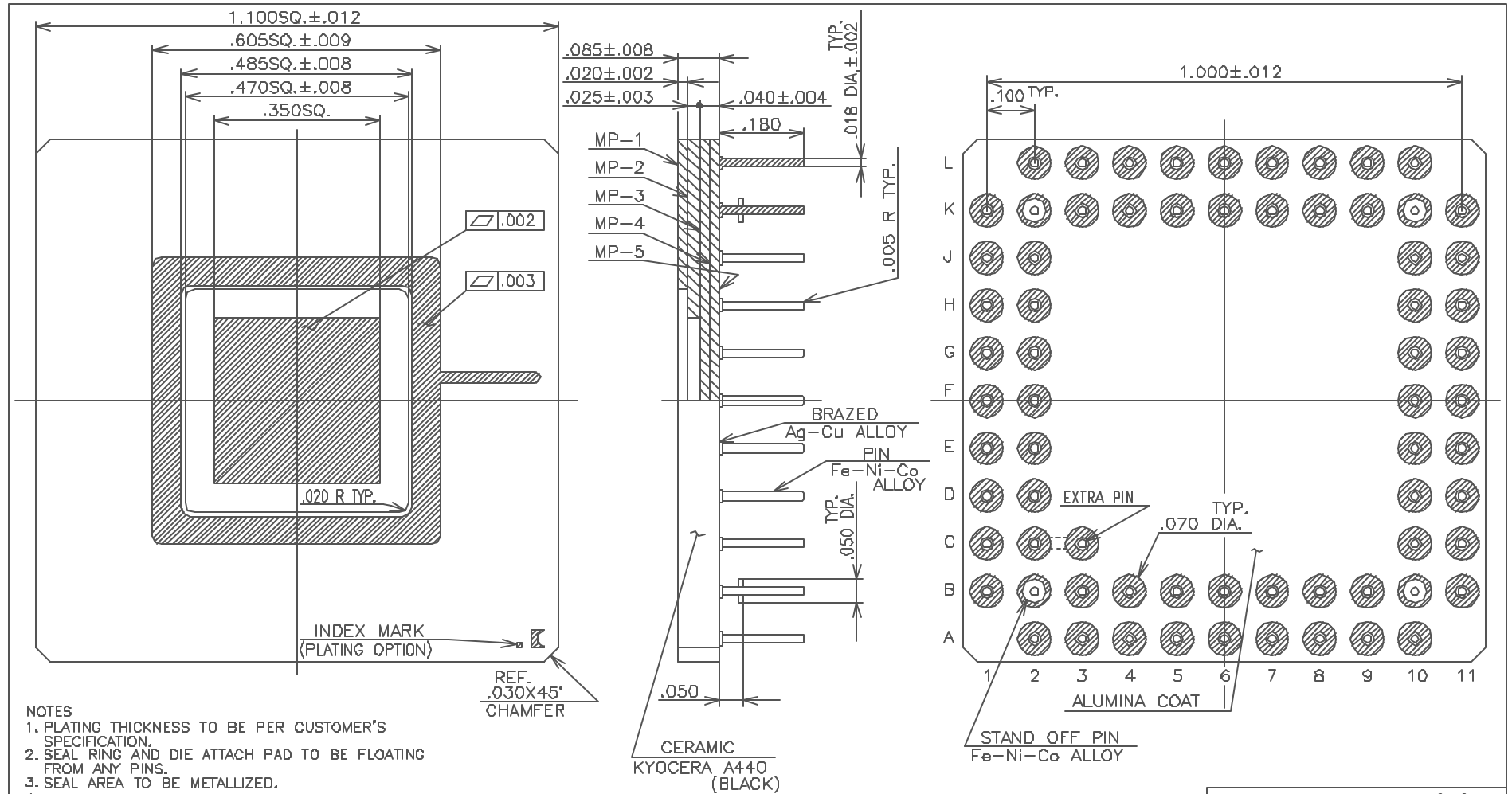


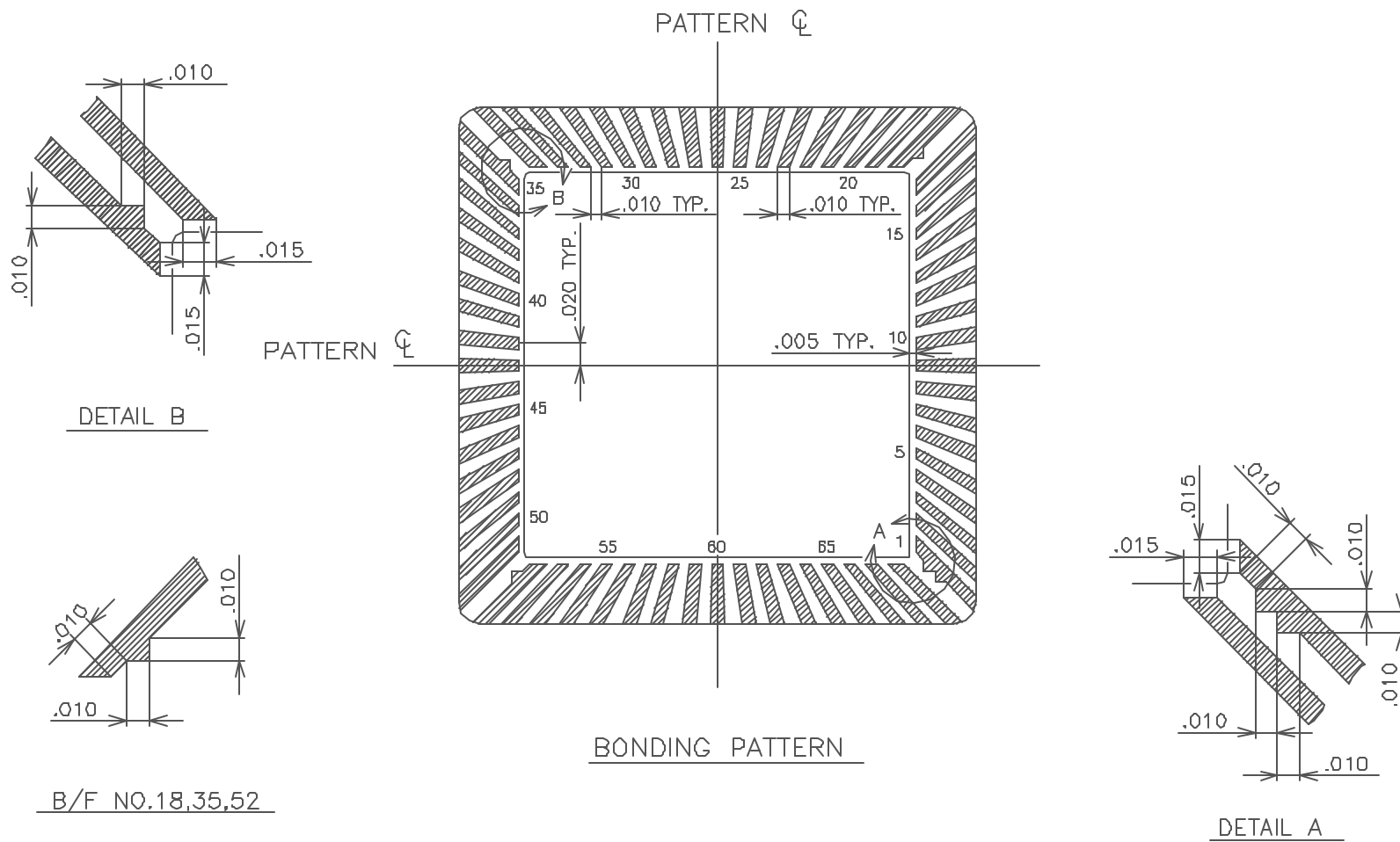
SSM P/N CPG06845



- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  2. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
  3. SEAL AREA TO BE METALLIZED.
  4. DIE ATTACH AREA TO BE METALLIZED.
  5. LEAD RESISTANCE: 500m OHM MAX.

MODIFICATION					NAME		TOLERANCE		PB069S754-1				S=0	
					69 PIN GRID ARRAY PACKAGE		UNLESS OTHERWISE SPECIFIED		±.005		DRAWN			
REDRAWN : CONVERTED CAD DATA. CHANGED					SCALE		MATERIAL		DRAWN		CHECKED		APPROVED	
					5 / 1		AS INDICATED		S.M		S.A		T.A	
SEP.24.'86 Y.T HLT/S.K H.SA					KYOCERA		KYOCERA CORPORATION KYOTO JAPAN		AUG.25.'86				9 SHEET 1 / 3	





MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						69 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.M	S.A	T.A	AUG.25.'86
						SCALE 10 / 1	MATERIAL				
	△ REDRAWN : CONVERTED CAD DATA.	SEP.24.'89	Y.T	H.T/S.K	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET 2 / 3	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-P86754-A			




WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

BONDING PAD	PIN No.
1	B2
2	B1
3	C2
4	C1
5	D2
6	D1
7	E2
8	E1
9	F2
10	F1
11	G2
12	G1
13	H2
14	H1
15	J2
16	J1
17	K1
18	K2
19	L2
20	K3
21	L3
22	K4
23	L4

BONDING PAD	PIN No.
24	K5
25	L5
26	K6
27	L6
28	K7
29	L7
30	K8
31	L8
32	K9
33	L9
34	L10
35	K10
36	K11
37	J10
38	J11
39	H10
40	H11
41	G10
42	G11
43	F10
44	F11
45	E10
46	E11

BONDING PAD	PIN No.
47	D10
48	D11
49	C10
50	C11
51	B11
52	B10
53	A10
54	B9
55	A9
56	B8
57	A8
58	B7
59	A7
60	B6
61	A6
62	B5
63	A5
64	B4
65	A4
66	B3
67	A3
68	A2

EXTRA PIN C3	C2
S/R	NC
D/A	NC

MODIFICATION						NAME	69 PIN GRID ARRAY PACKAGE	TOLERANCE	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE	$\times$	MATERIAL		S.M	S.A	T.A	AUG.25.'86
									THIRD ANGLE PROJECTION				
	$\Delta$	REDRAWN : CONVERTED CAD DATA. CHANGED	SEP.24.'90	Y.T	H.T/S.K	H.SA		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO.	KD-P86754-A		SHEET
		DATE	DRAWN	CHECKED	APPROVED								

